

Application for Semiconductor Topography (Micro Chips)

1.	Application fee:		2. Your reference (The applicant's or the representative's):	
3.	3. Title of the chip:			
4.	Applicant details (full name and adress):		☐ Additional applicants on reverse side	
	CVR-nr.: Tel.: (Residence)	P-number: Tel.:(Work)	E-mail: Mobile:	
5.	The applicant's citizenship: a) when filing the application: b) when first used in commrce:			
6.	State in which the applicant operated a commercial business (EU states or states which fall within "Lov om halvlederprodukters topografi" (the Consolidate Topography Act), section 4 (2): a) when filing the application: b) when first used in commerce:			
7.	The applicant's topography right: a) □ The topography is made by a natural person stated as the applicant. b) □ The applicant has acquired the topography right through the creation of a person employed by the applicant or the applicant ordered the topography elsewhere. c) □ From the owner of the topography right, the applicant has acquired the right to commercially use the topography in all EU member states, and the first commercial use already occurred or will occur in a member state. d) □ The applicant has acquired the topography right by a natural or legal person, who as an applicant might have made a declaration as in 7a, b or c.			
8.	Use in commerce: The first use in commerce already occurred (day/month/year): Use in commerce has not occurred.			
9.	☐ The application relates to a topography which is a result of the creator's intellectual effort, and which is not common within the semiconductor industry.			

Danish Patent- and Trademark Office Helgeshøj Allé 81 DK - 2630 Taastrup Denmark

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Ministry of Industry, Business and Financial Affairs

10.	Trade secrets:
	 □ Part of the material identifying and illustrating the topography is declared to be a trade secret pursuant to the Consolidate Topography Act, section 8. □ Part of the filed enclosures is requested not to be public available pursuant to the Consolidate Topography Act, section 9, as the enclosures contain trade secrets not necessary for identifying or illustrating the topography or necessary for determining the date of the first use in commerce.
11.	Representative (full name, address and CVR number, if any):
12.	Name of an applicant who is entitled, on behalf of all applicants, to receive correspondence from the Danish Patent and Trademark Office (only if more than one applicant):
13.	Enclosed documents:
	a) Drawings or photos (two copies in A4-format):
	 □ Layouts for the manufacturing of the semiconductor product. □ Masks or part of masks for the manufacturing of the semiconductor product. □ Semiconductor layers.
	b) \square Please specify additional material for identifying or illustrating the topography (two copies):
	c) \square Power of Attorney for the representative (if any):
14.	Additional remarks:
15.	Signature of the applicant or the representative (date, name):
	Notes made by the Danish Patent and Trademark Office